



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

503.35443VX1
RECEIVED
#14/16
F.BELL
7/10/02
TO 2000 MAIL ROOM

Applicant(s): NAGAI, et al.

Serial No.: 09/493,210 ✓

Filed: January 28, 2000

For: CIRCUIT TAPE HAVING ADHESIVE FILM, SEMICONDUCTOR
DEVICE, AND A METHOD FOR MANUFACTURING THE
SAME

Group: 2827

Examiner: L. Cruz

SUPPLEMENTAL AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

July 5, 2002

Sir:

In response to the Communication mailed June 4, 2002, and supplementing
the Amendment filed April 15, 2002, please further amend the above-identified
application as follows:

IN THE SPECIFICATION

Please delete the paragraph added to page ⁸₁ after line 1, in the Amendment
filed April 15, 2002, and add the following new paragraph on page 8, after line 1, as
follows:

--Fig. 9 shows a semiconductor device with a three layer structure for the
adhesive layer. Shown is core layer (e.g., porous supporting layer) 10 with adhesive